

FEATURES

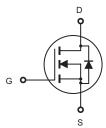
- $\bullet \mbox{High dense cell design for extremely low } R_{\mbox{\scriptsize DS(ON)}}$
- •Rugged and reliable
- •Case Material: Molded Plastic.

Absolute Maximum Ratings (TA=25°C, unless otherwise noted)

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	VDS	20	V
Gate-source Voltage	VGS	±8	V
Drain Current (Continuous)	ID	3	A
Drain Current (Pulsed) ^a	IDM	10	A
Total Power Dissipation @TA=25oC	PD	1.25	W
Operating Junction and Storage Temperature Range	$T_{j,} T_{stg}$	-55 to +150	°C
Thermal Resistance Junction to Ambient (PCB mounted) ^b	R _{JA}	100	°C/W

SI2302 N-Channel MOSFET





Electrical Characteristics (TA=25°C, unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit		
Off Characteristics								
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS} = 0V, I_D = 10\mu A$	20			V		
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 20V, V_{GS} = 0V$			1	μΑ		
Gate Body Leakage Current, Forward	I_{GSSF}	$V_{GS} = 8V, V_{DS} = 0V$			100	nA		
Gate Body Leakage Current, Reverse	Igssr	$V_{GS} = -8V, V_{DS} = 0V$			-100	nA		
On Characteristics ^c								
Gate Threshold Voltage	V _{GS(th)}	$V_{GS} = V_{DS}, I_D = 50\mu A$	0.65		1.2	V		
Static Drain-Source	R _{DS(on)}	$V_{GS} = 4.5 \text{V}, I_D = 3.6 \text{A}$		55	72	m		
On-Resistance	- DS(on)	$V_{GS} = 2.5 \text{V}, I_D = 3.1 \text{A}$		82	110	m		
Forward Transconductance	g_{FS}	$V_{DS} = 5V, I_D = 3.6A$		8.5		S		
Dynamic Characteristics ^d								
Input Capacitance	C _{iss}	$V_{DS} = 10V, V_{GS} = 0V, f = 1.0$ MHz		237		pF		
Output Capacitance	C _{oss}			120		pF		
Reverse Transfer Capacitance	C _{rss}			45		pF		
Switching Characteristics d								
Turn-On Delay Time	t _{d(on)}	$V_{DD} = 10V, I_D = 3.6A, V_{GS} = 4.5V, R_{GEN} = 6$		23	45	ns		
Turn-On Rise Time	t _r			11	30	ns		
Turn-Off Delay Time	$t_{d(off)}$			34	70	ns		
Turn-On Fall Time	$t_{ m f}$			36	70	ns		



Total Gate Charge	Q_{g}	$V_{DS} = 10V, I_D = 3.6A, V_{GS} = 4.5V$		6	10	nC		
Gate-Source Charge	Q_{gs}			1.4		nC		
Gate-Drain Charge	Q_{gd}			1.8		nC		
Drain-Source Diode Characteristics and Maximun Ratings								
Drain-Source Diode Forward Current ^c	I_S				0.94	A		
Drain-Source Diode Forward Voltage ^d	V _{SD}	$V_{GS} = 0V, I_S = 0.94A$			1.2	V		

 $a. Repetitive\ Rating: Pulse\ width\ limited\ by\ maximum\ junction\ temperature. \qquad b. Surface\ Mounted\ on\ FR4\ Board, t<10\ sec.$

ME2302 Typical Characteristics

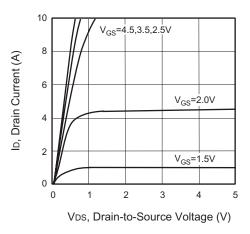


Figure 1. Output Characteristics

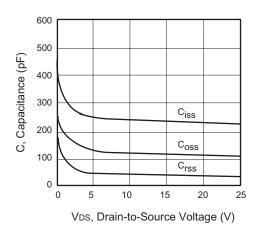


Figure 3. Capacitance

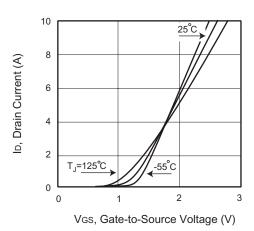


Figure 2. Transfer Characteristics

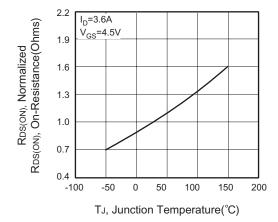


Figure 4. On-Resistance Variation with Temperature

c.Pulse Test: Pulse Width < 300µs, Duty Cycle < 2%. d.Guaranteed by design, not subject to production testing.



ME2302 Typical Characteristics

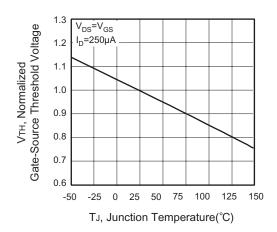


Figure 5. Gate Threshold Variation with Temperature

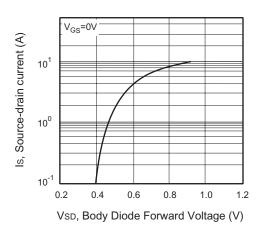


Figure 6. Body Diode Forward Voltage Variation with Source Current

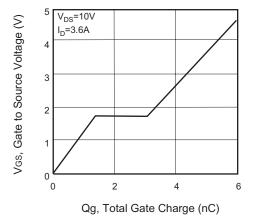


Figure 7. Gate Charge

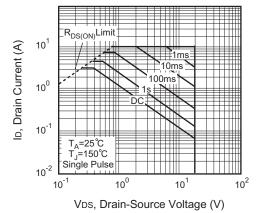


Figure 8. Maximum Safe Operating Area